# 506986731 11/19/2021

# **PATENT ASSIGNMENT COVER SHEET**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
HCP PACKAGING HONG KONG LTD.	01/16/2020

### **RECEIVING PARTY DATA**

Name:	SHISEIDO AMERICAS CORPORATION		
Street Address:	390 MADISON AVENUE		
City:	NEW YORK		
State/Country:	NEW YORK		
Postal Code:	10017		

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	29811854

#### **CORRESPONDENCE DATA**

**Fax Number:** (856)267-5370

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using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	S2099-46US		
NAME OF SUBMITTER:	KRISTYNE A BULLOCK		
SIGNATURE:	/kab/		
DATE SIGNED:	11/19/2021		

## **Total Attachments: 4**

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PATENT 506986731 REEL: 058160 FRAME: 0947

#### ASSIGNMENT

WHEREAS, HCP Packaging Hong Kong Ltd., a private limited corporation under the laws of Hong Kong, having a place of business at Leighton Centre, Room 1317, Causeway Bay, Hong Kong, hereinafter generally referred to as "ASSIGNOR," is the owner of a certain designs for which were executed design patent applications and registrations throughout the world as set forth in Appendix A hereto,

#### AND WHEREAS,

Shiseido Americas Corporation, a Delaware Corporation, having a place of business of 390 Madison Avenue, New York, New York, United States of America, hereinafter generally referred to as "ASSIGNEE," is desirous of acquiring said designs and said applications for patent and registrations listed in Appendix A and the designs embodied therein,

NOW, THEREFORE, in consideration of the sum of One Dollar and other good and valuable executed consideration, the full receipt and sufficiency of all of which are hereby acknowledged, and intending to be legally bound hereby, ASSIGNOR, hereby agrees to sell, assign, transfer and convey and by these presents does sell, assign, transfer and convey unto the above-named ASSIGNEE, the whole and entire right, title and interest

in and to said designs as described and/or claimed in the applications for patent and registration listed in Appendix A and for all countries and regions of the world, including the territory of the United States and its possessions and territories;

in and to the applications for patent and registration listed in Appendix A and any patent applications, applications for registration, patents and registrations which may be granted on said design or on any of related applications for patent or registration, including non-provisionals, divisionals, continuations, continuations-in-part, reissues, reexamination certificates and extensions, industrial designs, registrations, utility models, petty patents, and specifically including all rights of priority created by the above applications, patents, models or registrations, under any treaty, convention or law relating thereto;

and together with all claims for damages by reason of past infringement of said applications, registrations, and/or Letters Patents with the right to sue for and collect the same for its own use and behalf or for the use and behalf of its legal representatives;

said design, applications, registrations, models, and patent(s) to be held and enjoyed by the above-named ASSIGNEE, for ASSIGNEE's own use and benefit, and for ASSIGNEE's legal representatives and assigns to the full end of the term or terms for which said patent(s) or registration(s) may be granted, as fully and entirely as the same would have been held by the undersigned ASSIGNOR had this assignment and sale not been made; and for the aforesaid consideration ASSIGNOR hereby covenants, agrees and undertakes to execute, whenever requested by the above-named ASSIGNEE, all applications, patents, registration, assignments, lawful oaths and any other papers which ASSIGNEE may deem necessary or desirable for

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securing to ASSIGNEE or for maintaining for ASSIGNEE all the patent(s) or registration(s) hereby assigned or agreed to be assigned; all without further compensation to the undersigned ASSIGNOR.

ASSIGNOR WARRANTS and REPRESENTS that no assignment, grant, mortgage, license or other agreement or encumbrance affecting the rights and property herein conveyed has been or will be made to others by ASSIGNOR, and that the full right to convey the same as herein expressed is possessed by ASSIGNOR and is hereby transferred to ASSIGNEE;

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securing to ASSIGNEE or for maintaining for ASSIGNEE all the patent(s) or registration(s) hereby assigned or agreed to be assigned; all without further compensation to the undersigned ASSIGNOR.

ASSIGNOR WARRANTS and REPRESENTS that no assignment, grant, mortgage, license or other agreement or encumbrance affecting the rights and property herein conveyed has been or will be made to others by ASSIGNOR, and that the full right to convey the same as herein expressed is possessed by ASSIGNOR and is hereby transferred to ASSIGNEE;

			HCP Packaging Hong Kong Ltd	
Date			Signature	
			Typed or Printed Name	:: ::
			Title	***********
cknowledged	and Accented			
···	***************************************		Shiseido Americas Corporation	
)AVVANZA 19	-,2026		Mars Qua	
Date J		****	Signature	
			MARIA CHICLANA	
			Typed or Printed Name	
			Senior Vice President, General Co.	<u>iajel – </u>
			Title Co	

# APPENDIX A

Jurisdiction	Filing Date	Priority/Paris Convention Filing Date	Application/Registration No.		
United States	11 October 2019	same	Appln. No. 29/709,158		
Australia	24 October 2019	11 October 2019	Reg. No. 201916094		
Canada	29 October 2019	11 October 2019	Reg. No. 190816		
China	7 November 2019	11 October 2019	Appln. No. 201930612494.2		
European Community Design	15 October 2019	11 October 2019	Reg. No. 007 021 357		
Hong Kong	5 November 2019	11 October 2019	Appin. No. 1914949.9		
Japan	14 November 2019	11 October 2019	Appln. No. 2019-025342		

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PATENT REEL: 058160 FRAME: 0951